

MATERIAL DECLARATION SHEET



Material Number	PTVS10-058C-TH			
Product Line	Semiconductor Products			
Compliance Date	November 30 th 2013			
RoHS Compliant	Yes	MSL	Not Applicable	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.558194	Bisphenol Epoxy Resin	1675-54-3	40.00	6.96	17.40
				Epoxy Resin	25085-99-8	20.00	3.48	
				Crystalline Silica	14464-46-1	23.00	4.00	
				Brominated Epoxy Resin	40039-93-8	12.00	2.09	
				Iron Oxide	51274-00-1	2.00	0.35	
				Titanium Oxide	13463-67-7	3.00	0.52	
2	Electrodes	Copper	1.781057	Copper	7440-50-8	99.10	55.03	55.53
				Silver	7440-22-4	0.40	0.22	
				Other	-	0.50	0.28	
3	Terminations	Copper	0.503168	Copper	7440-50-8	99.50	15.61	15.69
				Other	-	0.50	0.08	
4	Termination Finish	Silver	0.001952	Silver	7440-22-4	100.00	0.06	0.06
5	Chip	Silicon Die	0.147152	Silicon	7440-21-3	85.73	3.93	4.59
				Aluminium	7429-90-5	4.99	0.23	
				Nickel	7440-02-0	8.85	0.41	
				Gold	7440-57-5	0.43	0.02	
6	Die Attach	Solder	0.111586	Lead	7439-92-1	92.50	3.22	3.48
				Tin	7440-31-5	5.00	0.17	
				Silver	7440-22-4	2.50	0.09	
7	Die Coating	Silicone	0.104232	Polysiloxane	63148-62-9	22.11	0.72	3.25
				Chromium Sesquioxide	1308-38-9	5.67	0.18	
				Fumed Silica	112945-52-5	11.11	0.36	
				Filler	Trade Secret	61.11	1.99	
		Total Weight	3.207340					